NTD110N02R, STD110N02R

MOSFET – Power, N-Channel, DPAK

24 V, 110 A

Features

- Planar HD3e Process for Fast Switching Performance
- Low $R_{DS(on)}$ to Minimize Conduction Loss
- Low C_{iss} to Minimize Driver Loss
- Low Gate Charge
- Optimized for High Side Switching Requirements in High−Efficiency DC−DC Converters
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain−to−Source Voltage	V_{DSS}	24	V
Gate−to−Source Voltage − Continuous	V_{GS}	±20	V
Thermal Resistance − Junction−to−Case	$R_{\theta JC}$	1.35	°C/W
Total Power Dissipation @ T_C = 25°C	P_D	110	W
Drain Current			
− Continuous @ T_C = 25°C, Chip	I_D	110	A
− Continuous @ T_C = 25°C	I_D	110	A
Limited by Package			
− Continuous @ T_A = 25°C	I_D	32	A
Limited by Wires			
− Single Pulse (t_p = 10 μs)	I_D	110	A
Thermal Resistance			
− Junction−to−Ambient (Note 1)	$R_{\theta JA}$	52	°C/W
− Total Power Dissipation @ T_A = 25°C	P_D	2.88	W
− Drain Current − Continuous @ T_A = 25°C	I_D	17.5	A
Thermal Resistance			
− Junction−to−Ambient (Note 2)	$R_{\theta JA}$	100	°C/W
− Total Power Dissipation @ T_A = 25°C	P_D	1.5	W
− Drain Current − Continuous @ T_A = 25°C	I_D	12.5	A
Operating and Storage Temperature Range	T_J, T_{stg}	−55 to 175	°C
Single Pulse Drain−to−Source Avalanche Energy − Starting T_J = 25°C (V_{DD} = 50 Vdc, V_{GS} = 10 Vdc, I_L = 15.5 Apk, L = 1.0 mH, R_G = 25 Ω)	E_{AS}	120	mJ
Maximum Lead Temperature for Soldering Purposes, (1/8″ from case for 10 s)	T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. When surface mounted to an FR4 board using 0.5 sq in drain pad size.
2. When surface mounted to an FR4 board using the minimum recommended pad size.

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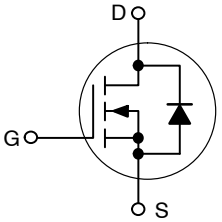
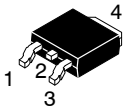
$V_{(BR)DSS}$	$R_{DS(on)}$ TYP	I_D MAX
24 V	4.1 mΩ @ 10 V	110 A

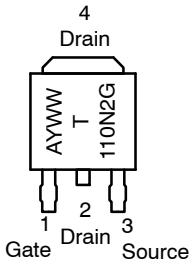


N−Channel



DPAK
CASE 369AA
(Surface Mount)
STYLE 2

MARKING DIAGRAM & PIN ASSIGNMENT



A	= Assembly Location*
Y	= Year
WW	= Work Week
T110N2	= Device Code
G	= Pb−Free Package

* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain−to−Source Breakdown Voltage (Note 3) (V_{GS} = 0 V, I_D = 250 μA) Positive Temperature Coefficient		$V_{(BR)DSS}$	24	28 15		V mV/°C
Zero Gate Voltage Drain Current (V_{DS} = 20 V, V_{GS} = 0 V) (V_{DS} = 20 V, V_{GS} = 0 V, T_J = 125°C)		I_{DSS}			 1.5 10	μA
Gate−Body Leakage Current (V_{GS} = ±20 V, V_{DS} = 0 V)		I_{GSS}			±100	nA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage (Note 3) (V_{DS} = V_{GS}, I_D = 250 μA) Negative Threshold Temperature Coefficient		$V_{GS(th)}$	1.0	1.5 5.0	2.0	V mV/°C
Static Drain−to−Source On−Resistance (Note 3) (V_{GS} = 10 V, I_D = 110 A) (V_{GS} = 4.5 V, I_D = 55 A) (V_{GS} = 10 V, I_D = 20 A) (V_{GS} = 4.5 V, I_D = 20 A)		$R_{DS(on)}$		 4.1 5.5 3.9 5.5	 4.6 6.2	mΩ
Forward Transconductance (V_{DS} = 10 V, I_D = 15 A) (Note 3)		g_{FS}		44		Mhos
DYNAMIC CHARACTERISTICS						
Input Capacitance	(V_{DS} = 20 V, V_{GS} = 0 V, f = 1.0 MHz)	C_{iss}		2710	3440	pF
Output Capacitance		C_{oss}		1105	1670	
Transfer Capacitance		C_{rss}		450	640	
SWITCHING CHARACTERISTICS (Note 4)						
Turn−On Delay Time	(V_{GS} = 10 V, V_{DD} = 10 V, I_D = 40 A, R_G = 3.0 Ω)	$t_{d(on)}$		11	22	ns
Rise Time		t_r		39	80	
Turn−Off Delay Time		$t_{d(off)}$		27	40	
Fall Time		t_f		21	40	
Gate Charge	(V_{GS} = 4.5 V, I_D = 40 A, V_{DS} = 10 V) (Note 3)	Q_T		23.6	28	nC
		Q_{GS}		5.1		
		Q_{GD}		11		
SOURCE−DRAIN DIODE CHARACTERISTICS						
Forward On−Voltage	(I_S = 20 A, V_{GS} = 0 V) (Note 3) (I_S = 55 A, V_{GS} = 0 V) (I_S = 20 A, V_{GS} = 0 V, T_J = 125°C)	V_{SD}		0.82 0.99 0.65	1.2	V
Reverse Recovery Time	(I_S = 30 A, V_{GS} = 0 V, dI_S/dt = 100 A/μs) (Note 3)	t_{rr}		36.5		ns
		t_a		30		
		t_b		25		
Reverse Recovery Stored Charge		Q_{rr}		0.048		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperatures.

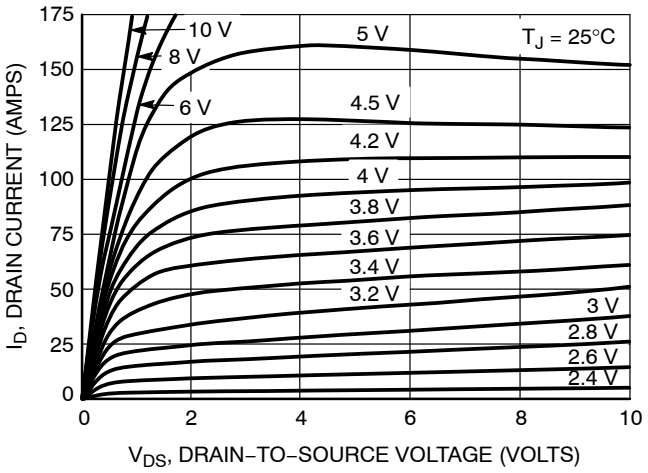


Figure 1. On−Region Characteristics

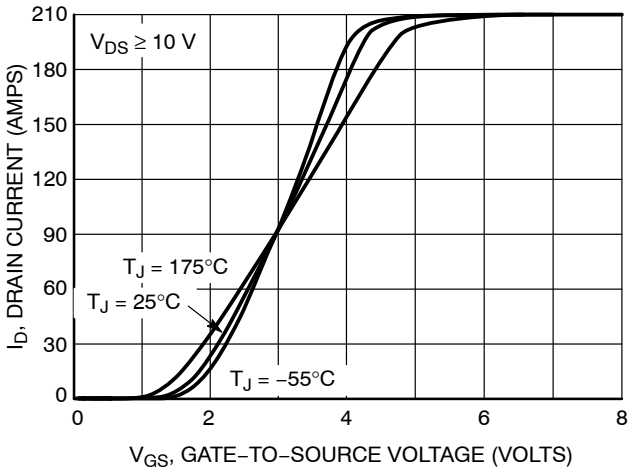


Figure 2. Transfer Characteristics

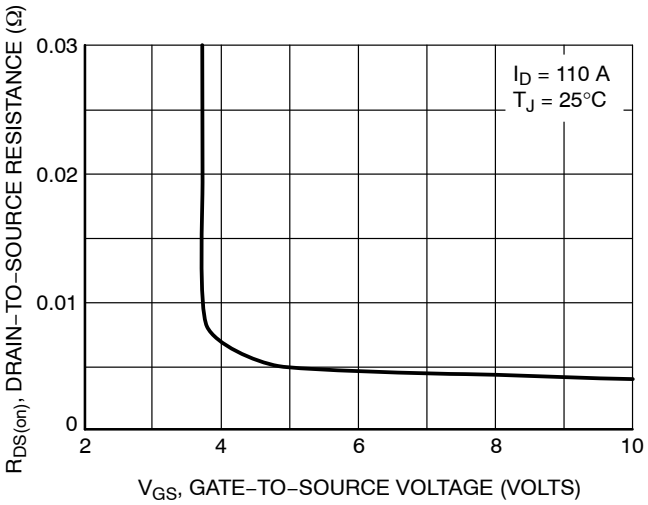


Figure 3. On−Resistance versus Gate−to−Source Voltage

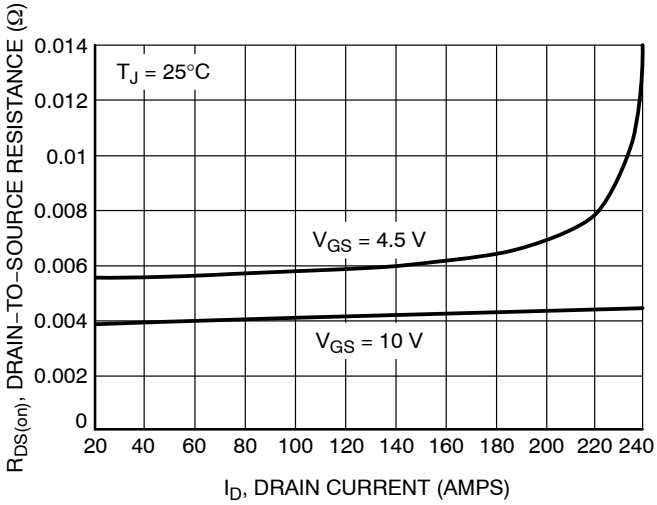


Figure 4. On−Resistance versus Drain Current and Gate Voltage

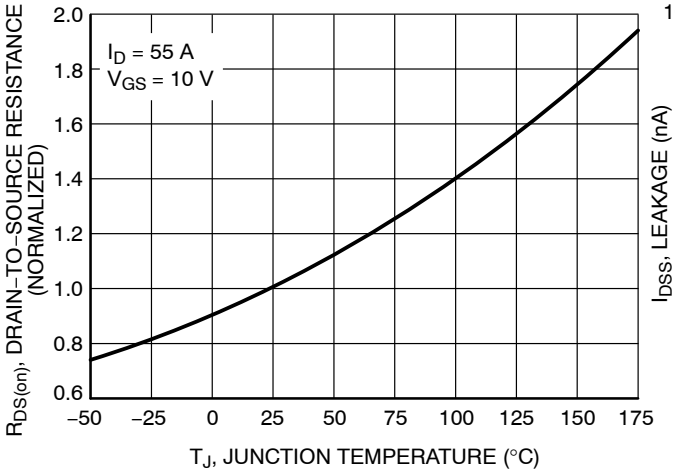


Figure 5. On−Resistance Variation with Temperature

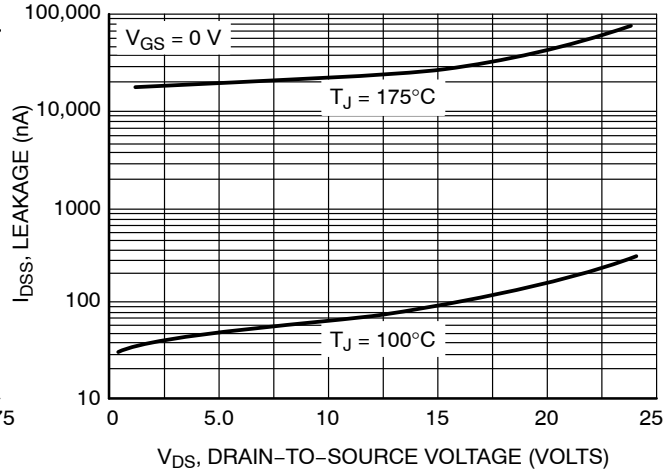


Figure 6. Drain−to−Source Leakage Current versus Voltage

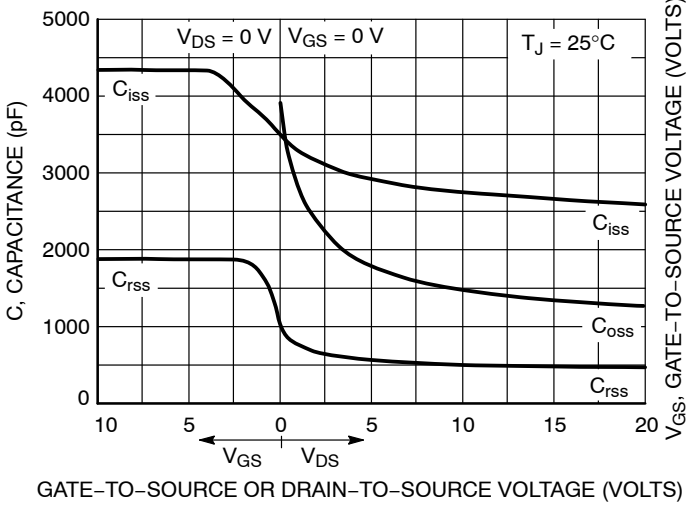


Figure 7. Capacitance Variation

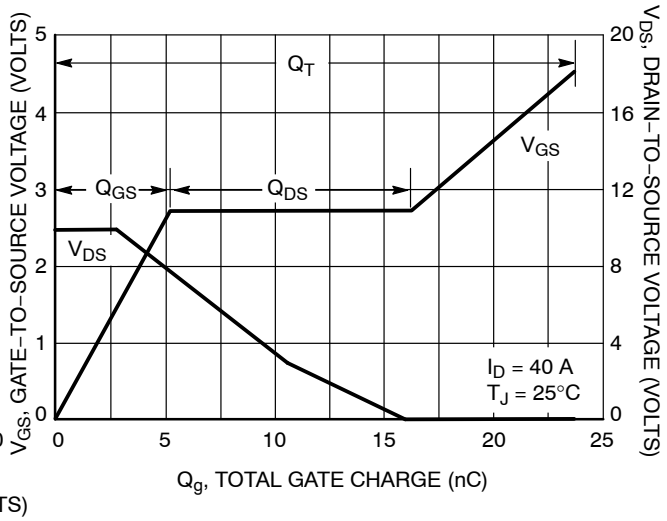


Figure 8. Gate−to−Source and Drain−to−Source Voltage versus Total Charge

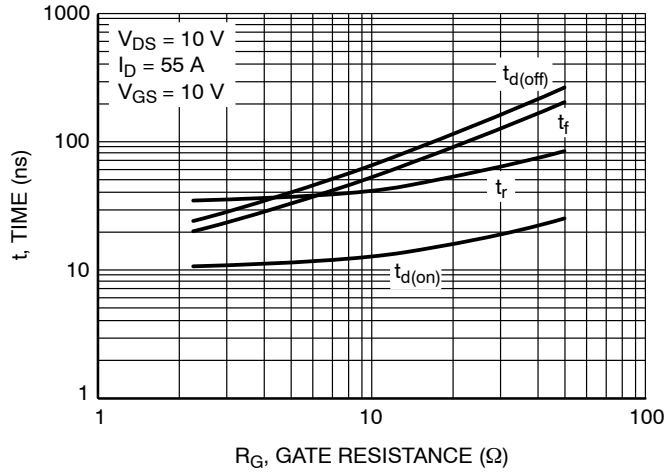


Figure 9. Resistive Switching Time Variation versus Gate Resistance

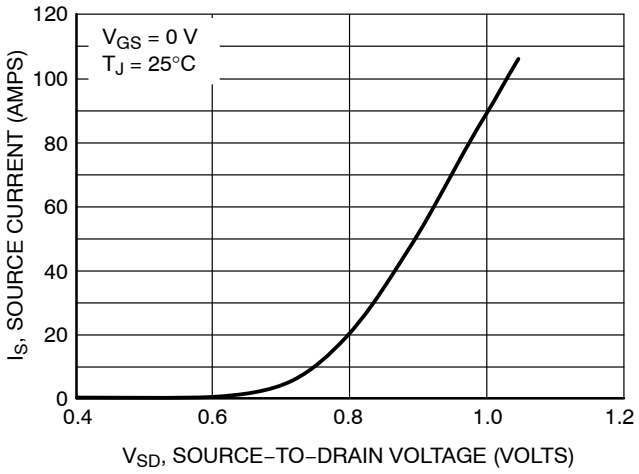


Figure 10. Diode Forward Voltage versus Current

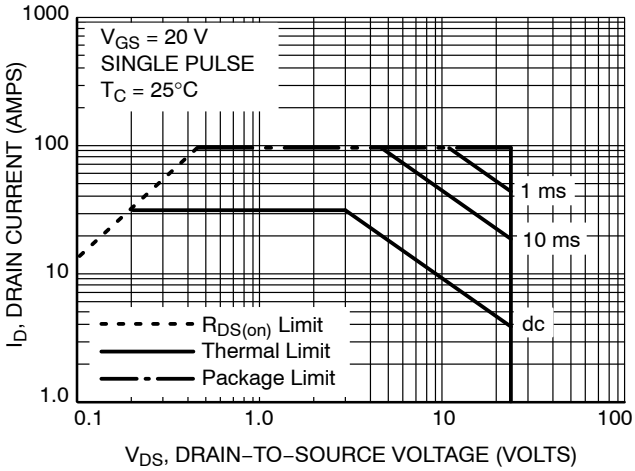


Figure 11. Maximum Rated Forward Biased Safe Operating Area

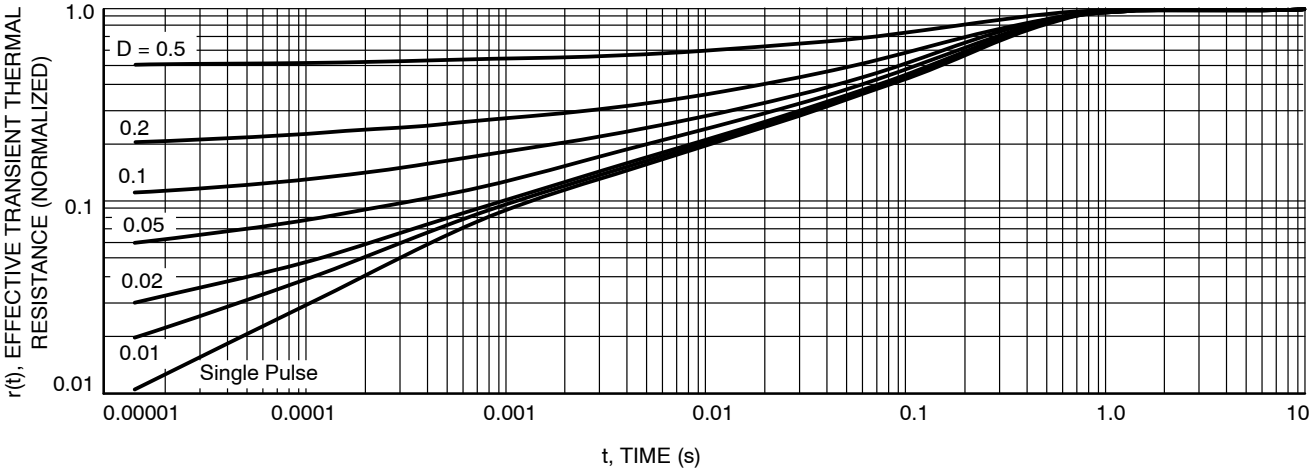


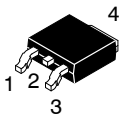
Figure 12. Thermal Response

ORDERING INFORMATION

Device	Package	Shipping†
NTD110N02RT4G	DPAK (Pb−Free)	2500 / Tape & Reel
STD110N02RT4G*	DPAK (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

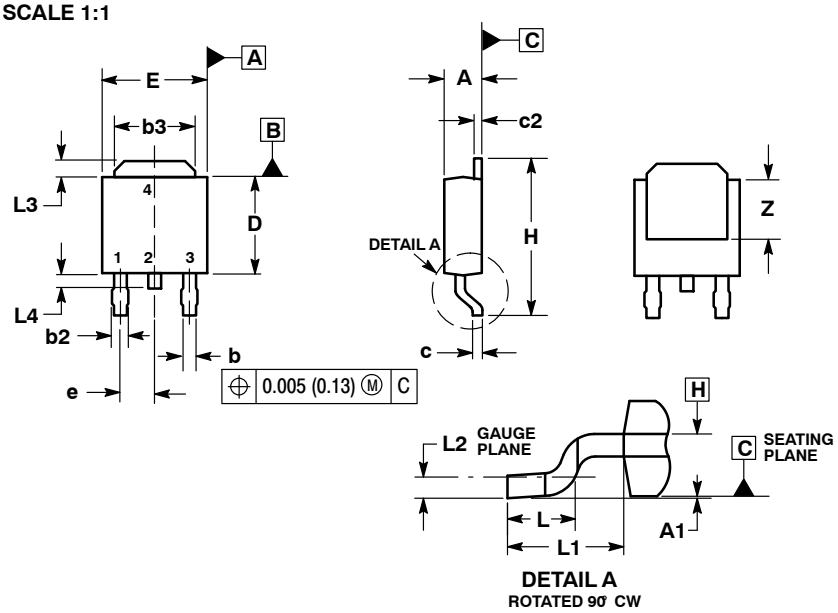
*S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable.



SCALE 1:1

DPAK (SINGLE GUAGE)
CASE 369AA
ISSUE B

DATE 03 JUN 2010



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

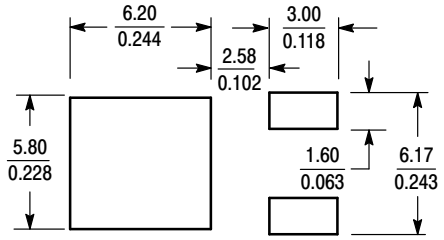
STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 5:
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE

STYLE 6:
PIN 1. MT1
2. MT2
3. GATE
4. MT2

STYLE 7:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

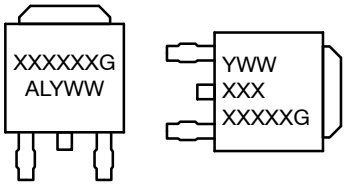
SOLDERING FOOTPRINT*



SCALE 3:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



IC **Discrete**

XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER:	**98AON13126D**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**DPAK (SINGLE GAUGE)**	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

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